



# SOT684-21

HVQFN56, plastic, thermally enhanced very thin quad flat package, no-leads, 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.85 mm body

3 December 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN56
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	30-10-2018
<b>Manufacturer package code</b>	98ASA01332D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	8	-	mm
package width	-	8	-	mm
seated height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



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2 Package outline

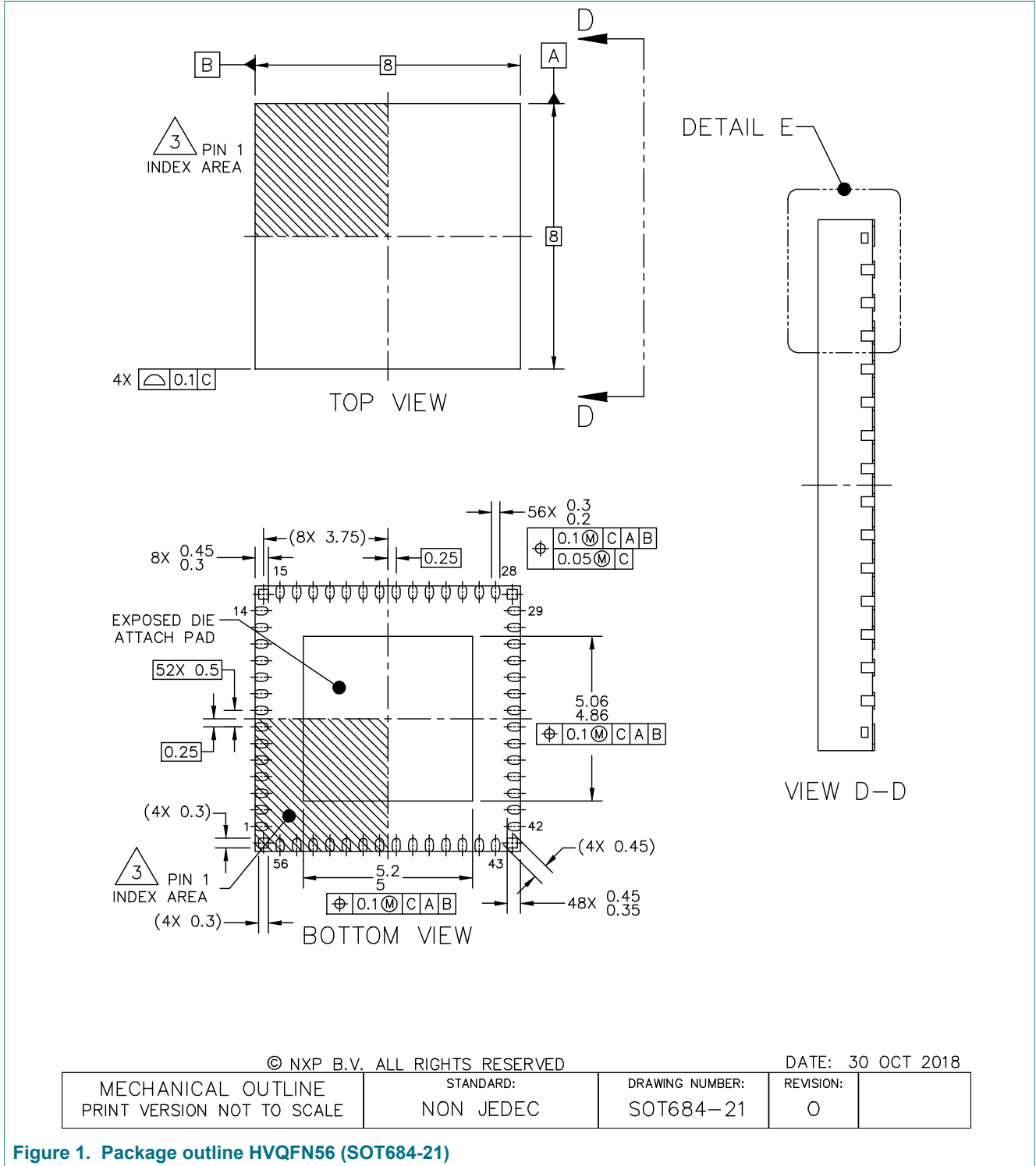


Figure 1. Package outline HVQFN56 (SOT684-21)

HVQFN56, plastic, thermally enhanced very thin quad flat package, no-leads, 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.85 mm body

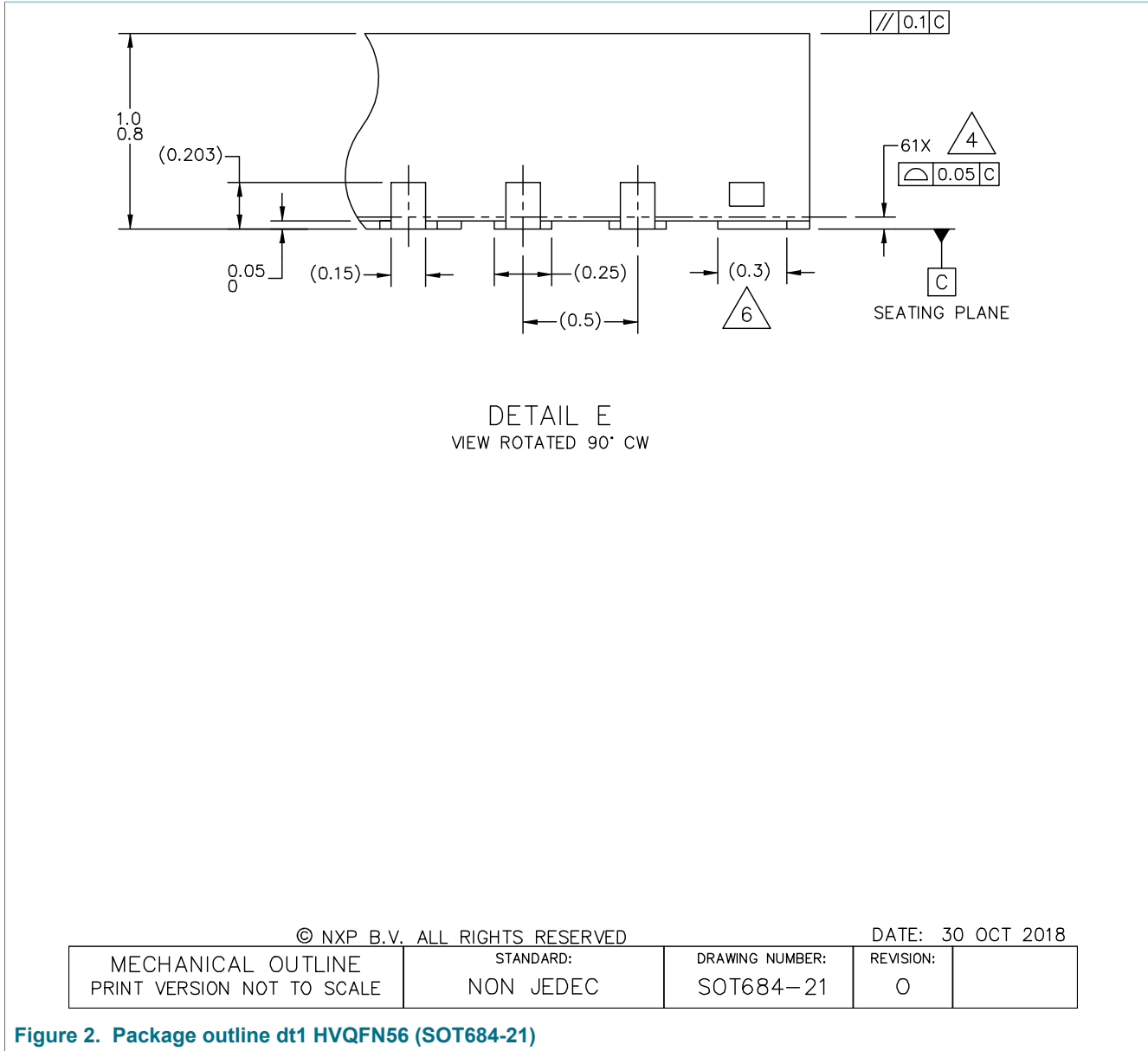
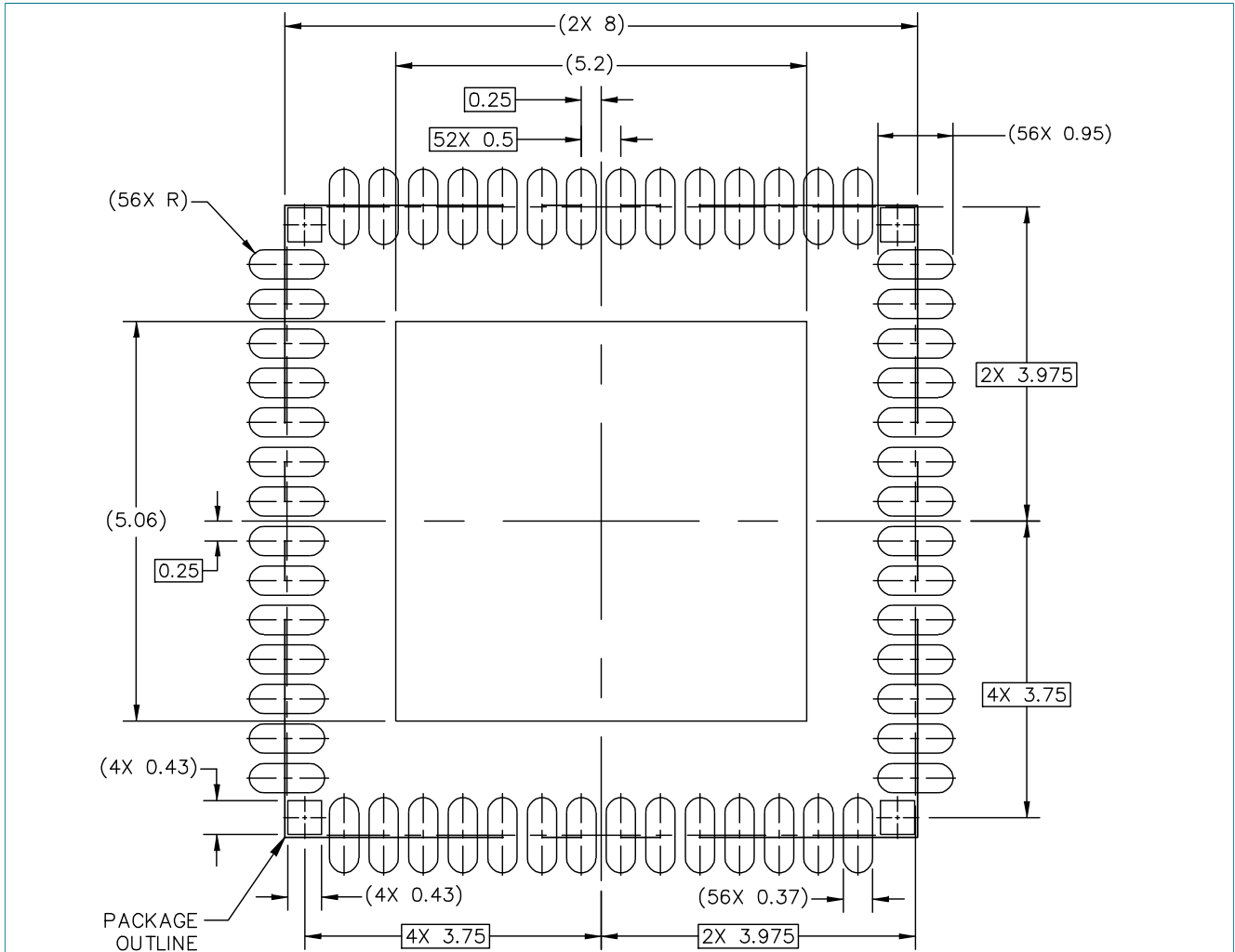


Figure 2. Package outline dt1 HVQFN56 (SOT684-21)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 30 OCT 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT684-21	REVISION: 0
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Figure 3. Reflow soldering footprint part1 for HVQFN56 (SOT684-21)

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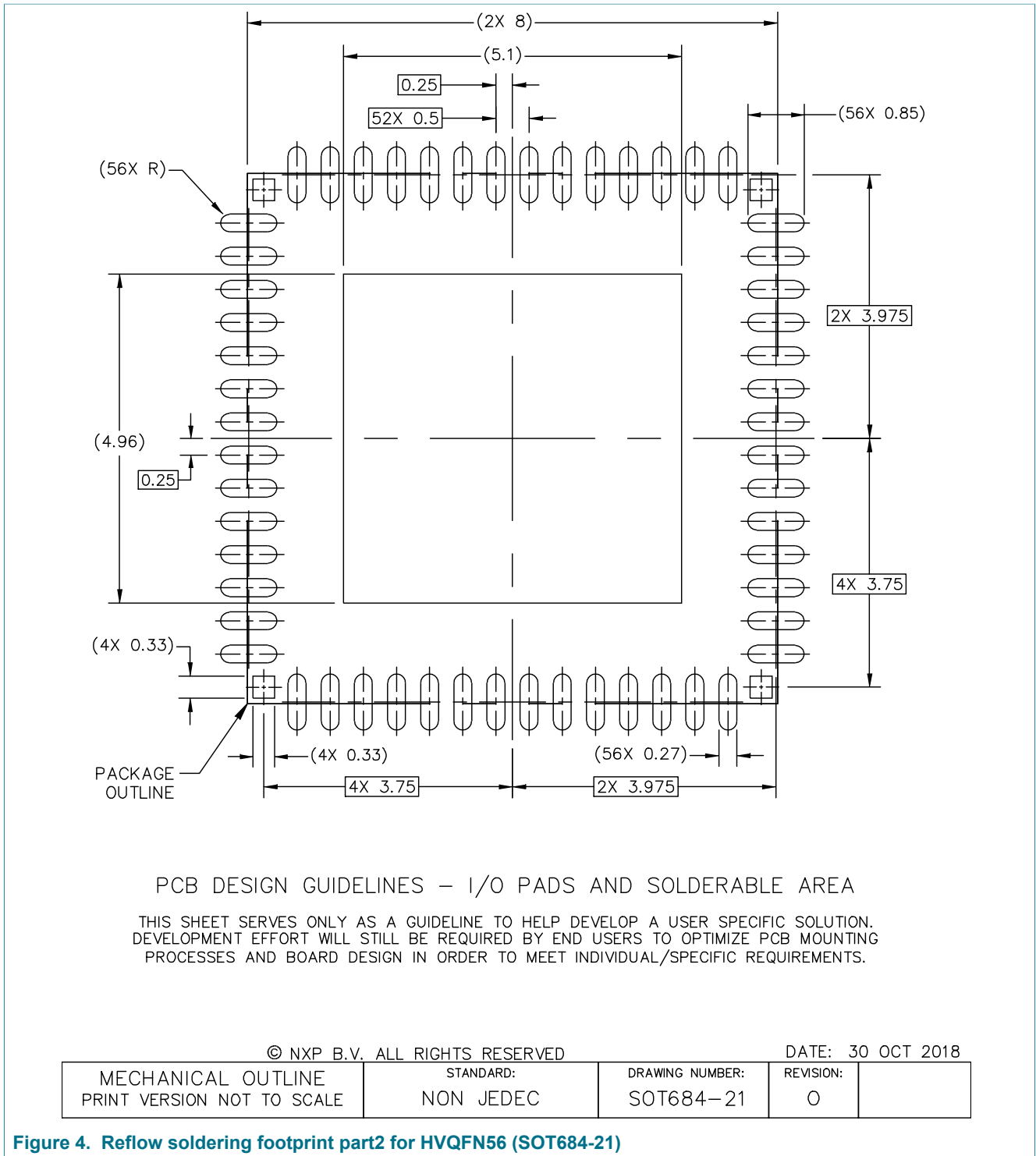


Figure 4. Reflow soldering footprint part2 for HVQFN56 (SOT684-21)

HVQFN56, plastic, thermally enhanced very thin quad flat package, no-leads, 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.85 mm body

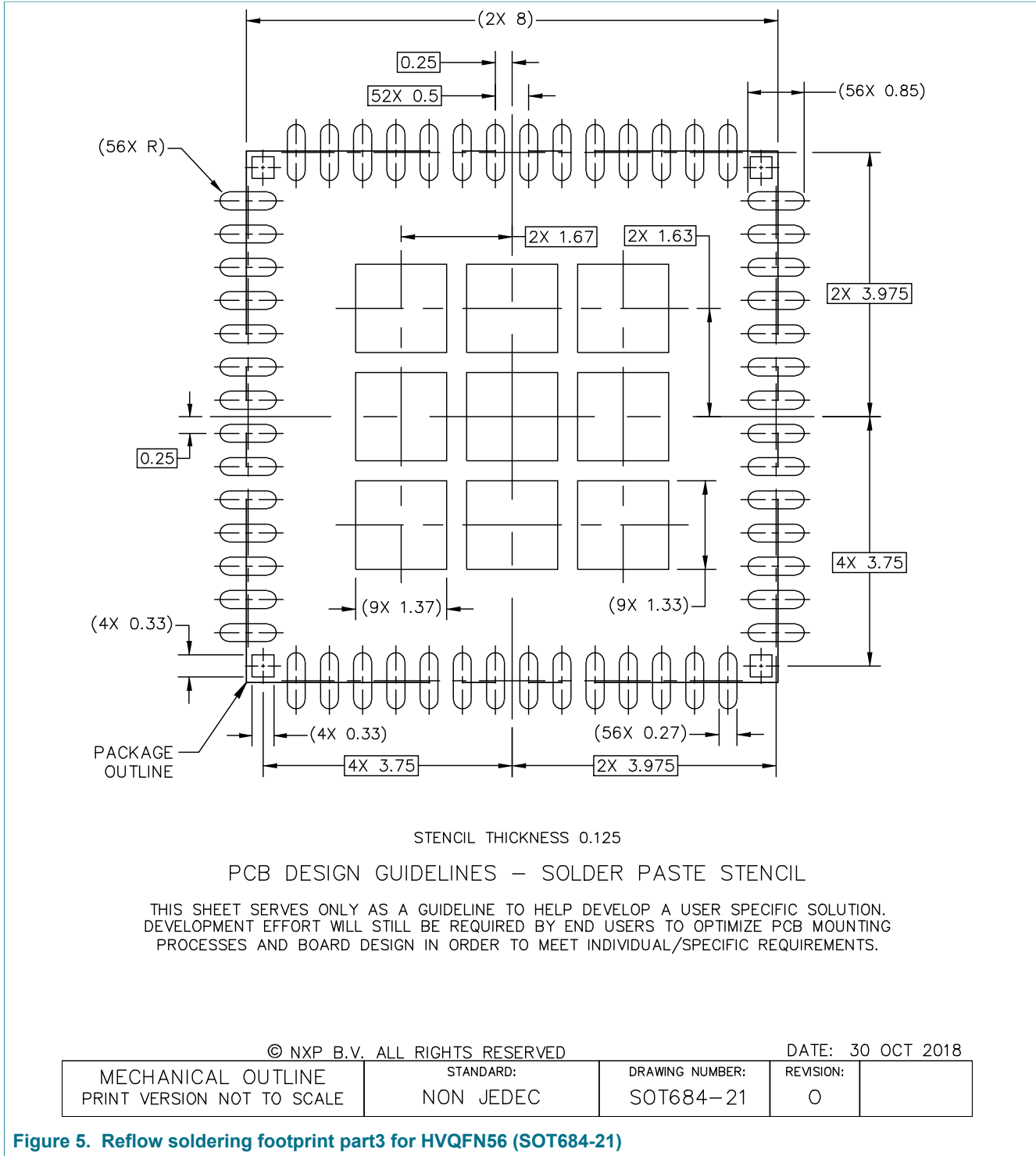


Figure 5. Reflow soldering footprint part3 for HVQFN56 (SOT684-21)

## 4 Legal information

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